



Material Content Data Sheet



Sales Product Name		BAS 70-04S H6327		Issued		2. August 2018		
MA#		MA000844142						
Package		PG-SOT363-6-3		Weight*		6.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		19	
	noble metal	gold	7440-57-5	0.012	0.19		1851	
	inorganic material	silicon	7440-21-3	0.102	1.58	1.77	15804	17674
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.003	0.05		480	
	non noble metal	chromium	7440-47-3	0.009	0.14		1439	
	non noble metal	copper	7440-50-8	3.093	47.78	47.98	477809	479824
wire	non noble metal	copper	7440-50-8	0.010	0.15	0.15	1470	1470
encapsulation	organic material	carbon black	1333-86-4	0.030	0.46		4579	
	plastics	epoxy resin	-	0.637	9.84		98445	
	inorganic material	silicondioxide	60676-86-0	2.297	35.49	45.79	354861	457885
leadfinish	non noble metal	tin	7440-31-5	0.213	3.29	3.29	32943	32943
plating	noble metal	silver	7440-22-4	0.066	1.02	1.02	10204	10204
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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